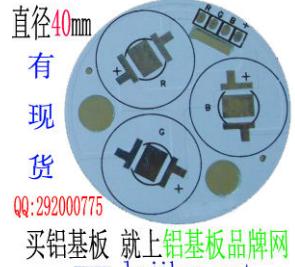
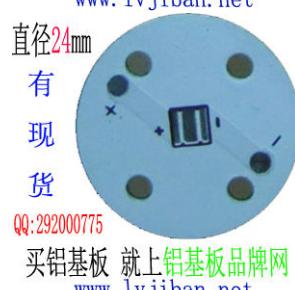
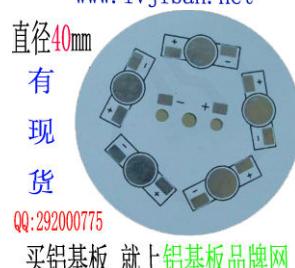
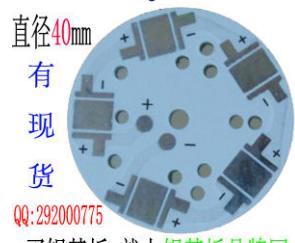
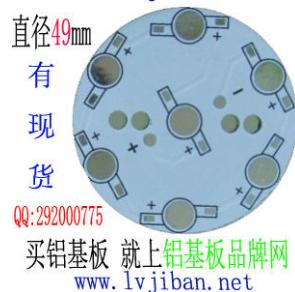
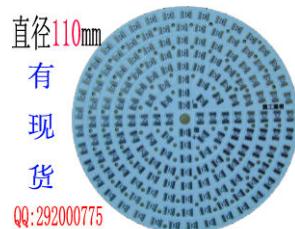
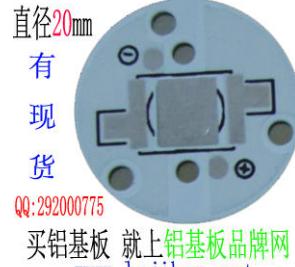
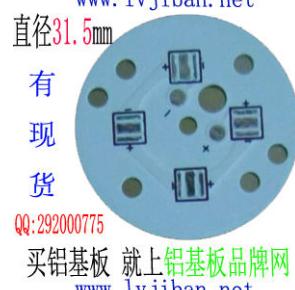
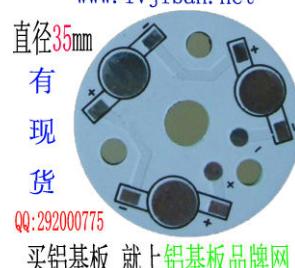
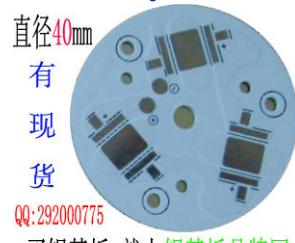
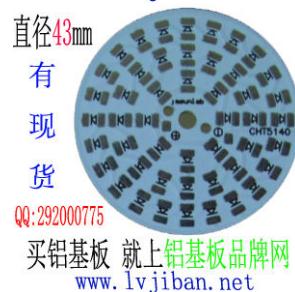
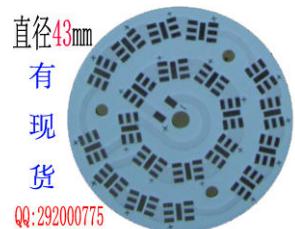
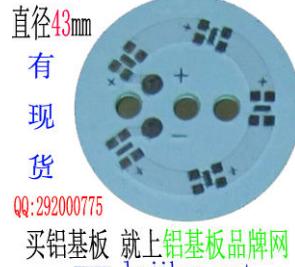
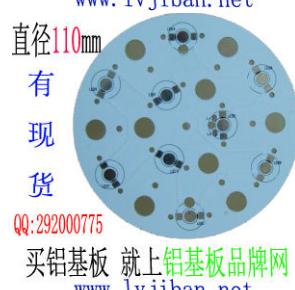
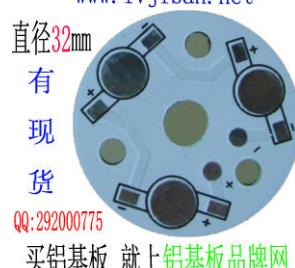
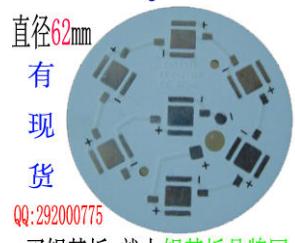
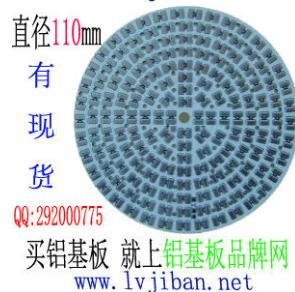
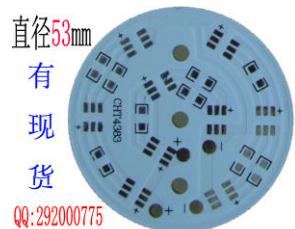
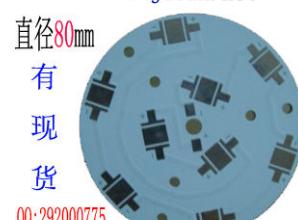
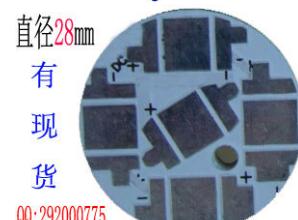
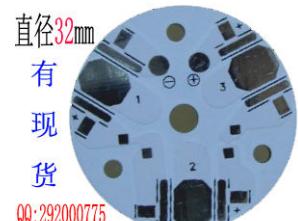
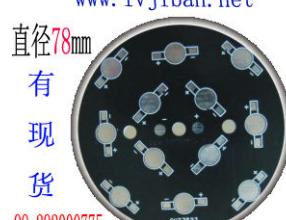
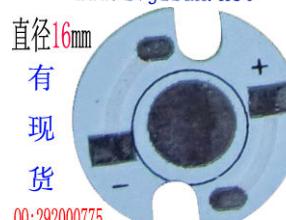
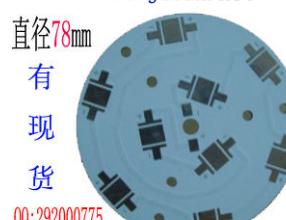
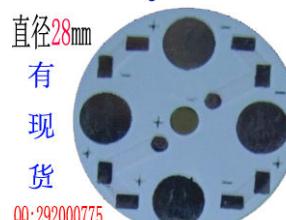
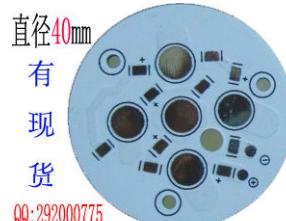
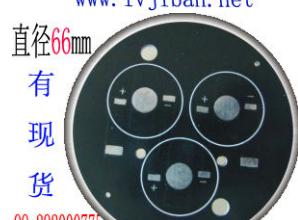
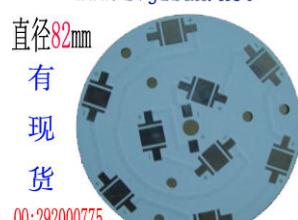
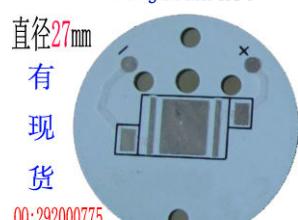
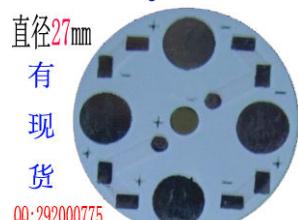
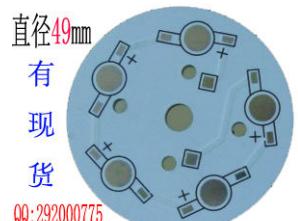


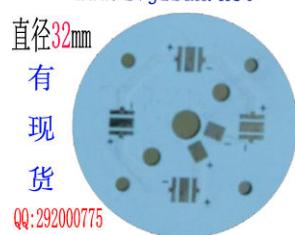
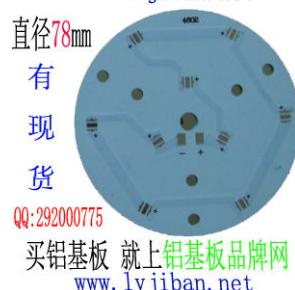
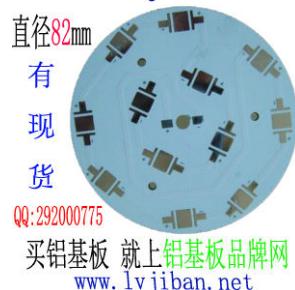
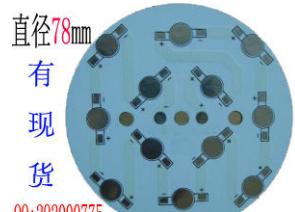
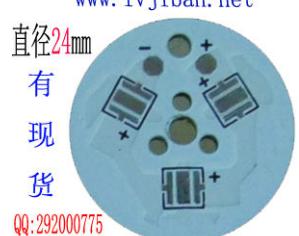
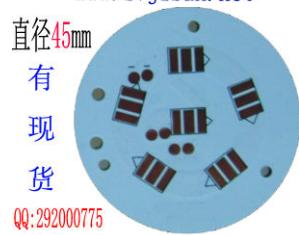
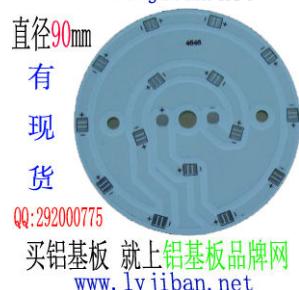
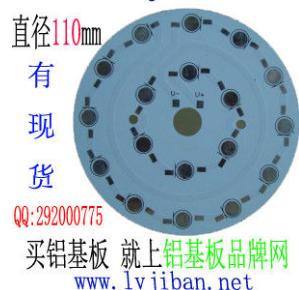
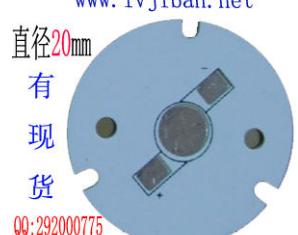
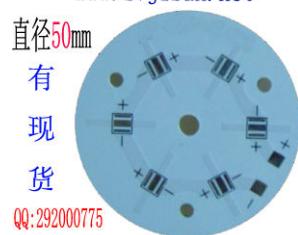
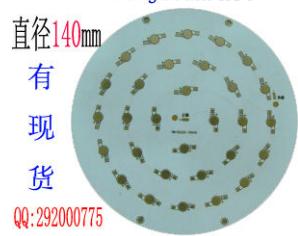
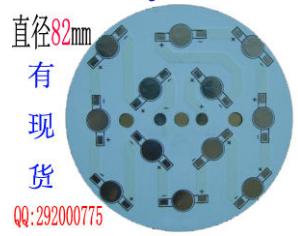
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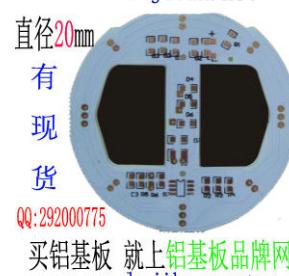
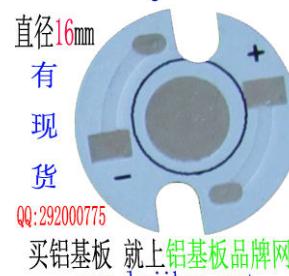
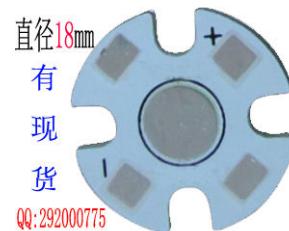
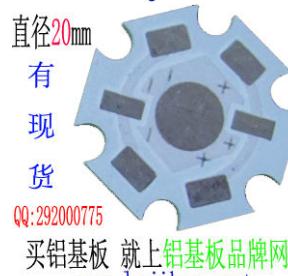
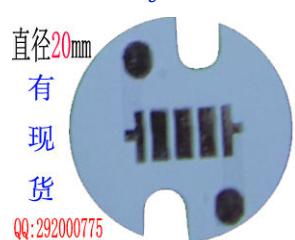
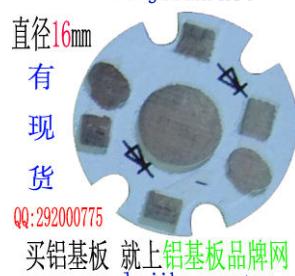
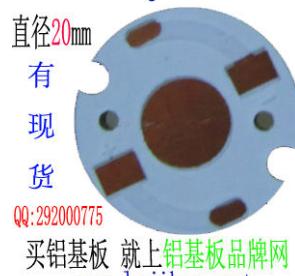


小强铝基板制作



小强铝基板制作





铝基板现货和铝基板库存图

铝基板测试项目

铝基板在线订购 www.lvjiban.net

Item 实验条件

Conditions 典型值

Typical Value 厚度

Thickness 性能参数

剥离强度

Peel strength(kgf/cm) A ≥1.5 50-150

耐焊锡性

Solder Resistance(s) 288°C 2min dipping 不分层，不起泡

No delamination and no bubble 50-150

绝缘击穿电压

Dielectric Breakdown voltage (Kv) D-48/50+D-0.5/23 ≥ 4.6 75

热阻

Thermal resistance (°C/W) ASTM D5470 0.175 142

热阻抗

Thermal impedance (*cm²/W) ASTM D5470 1.68 142

导热系数

Thermal Conductivity(w/mk) ASTM D5470 ≥ 2.0 50-150

表面电阻

Surface resistance(Ω) C-96/35/90 ≥ 10¹² 50-150

体积电阻

Volume resistance(Ω) ≥ 10¹² 50-150

介电常数

Dk 1MHz C-24/23/50 ≤ 5.0 50-150

介电损耗

Dk 1MH ≤ 0.05 50-150

耐燃性

Flammability UL94 VO PASS 50-150

CTI(Volt) IEC 60112600 50-150

※以上厚度仅为胶层厚度，不包括铜箔与铜板。

结构

绝缘层厚：75 um±% 导体厚：35um±10%

金属板厚：1.0mm±0.1mm

铝基板生产能力 铝基板在线订购 www.lvjiban.net

最大加工面积 Max.Board Size 23inch * 35inch

板厚 Board Thickness 0.4-6.0mm

最小线宽 Min.Line Width 0.10mm

最小间距 Min.Space 0.10mm

最小孔径 Min.Hole Size 0.15mm

孔壁铜厚 PTH Wall Thickness >0.025mm

金属化孔径公差 PTH Hole Dia.Tolerance ±0.05mm

非金属化孔径公差 Non PTH Hole Dia.Tolerance ±0.05mm

孔位公差 Hole Position Deviation ±0.076mm

外形尺寸公差 Outline Tolerance ±0.1mm

开槽 V-cut 30° /45° /60°

最小 BGA 焊盘 Min.BGA PAD 14mil

PCB 交流阻抗控制 Impedance control PCB ≤50 Ω ±5 Ω

>50 Ω ±10%

阻焊层最小桥宽 Soldermask Layer Min.Bridge width 5mil

阻焊膜最小厚宽 Soldermask film Min.Thickness 10mil

绝缘电阻 Insulation Resistance 1012 Ω(常态)Normal

抗剥强度 Peel-off Strength 1.4N/mm

阻焊剂硬度 Soldermask Abrasion >5H

热衝击测试 Solderability Test 260°C 20(秒)second

通断测试电压 E-test Voltage 50-250V

介电常数 Permitivity $\epsilon = 2.1 \sim 10.0$

体积电阻 Volume resistance 10¹⁴ Ω ·m,ASTM D257,IEC60093